

RJK5018DPK

Silicon N Channel MOS FET
High Speed Power Switching

REJ03G1457-0100

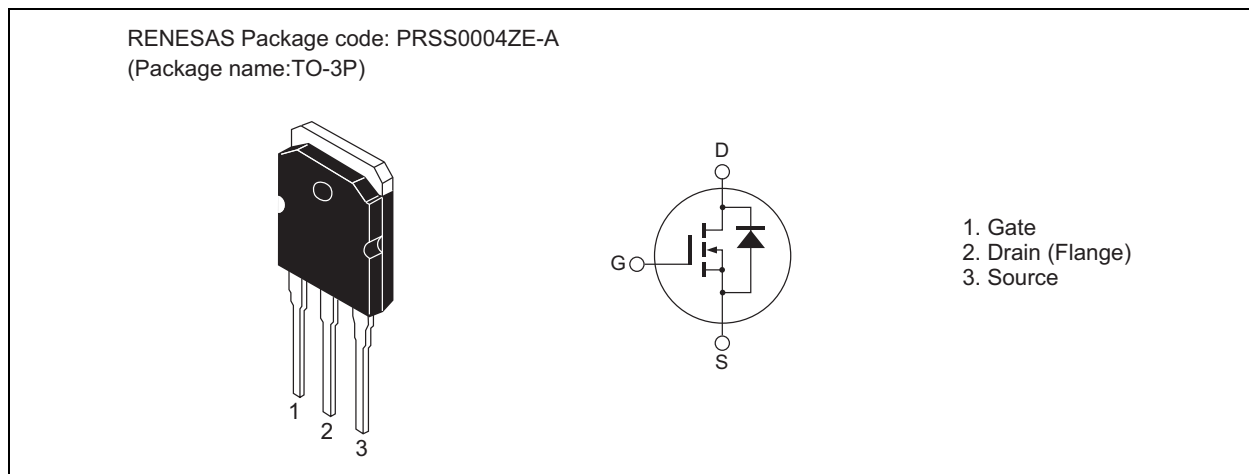
Rev.1.00

May 11, 2006

Features

- Low on-resistance
- Low leakage current
- High speed switching

Outline



Absolute Maximum Ratings

(Ta = 25°C)

Item	Symbol	Ratings	Unit
Drain to source voltage	V _{DSS}	500	V
Gate to source voltage	V _{GSS}	±30	V
Drain current	I _D	35	A
Drain peak current	I _{D (pulse)} ^{Note1}	105	A
Body-drain diode reverse drain current	I _{DR}	35	A
Body-drain diode reverse drain peak current	I _{DR (pulse)} ^{Note1}	105	A
Avalanche current	I _{AP} ^{Note3}	9	A
Avalanche energy	E _{AR} ^{Note3}	4.5	mJ
Channel dissipation	P _{ch} ^{Note2}	200	W
Channel to case thermal impedance	θ _{ch-c}	0.625	°C/W
Channel temperature	T _{ch}	150	°C
Storage temperature	T _{stg}	-55 to +150	°C

Notes: 1. PW ≤ 10 μs, duty cycle ≤ 1%

2. Value at T_c = 25°C

3. ST_{ch} = 25°C, T_{ch} ≤ 150°C

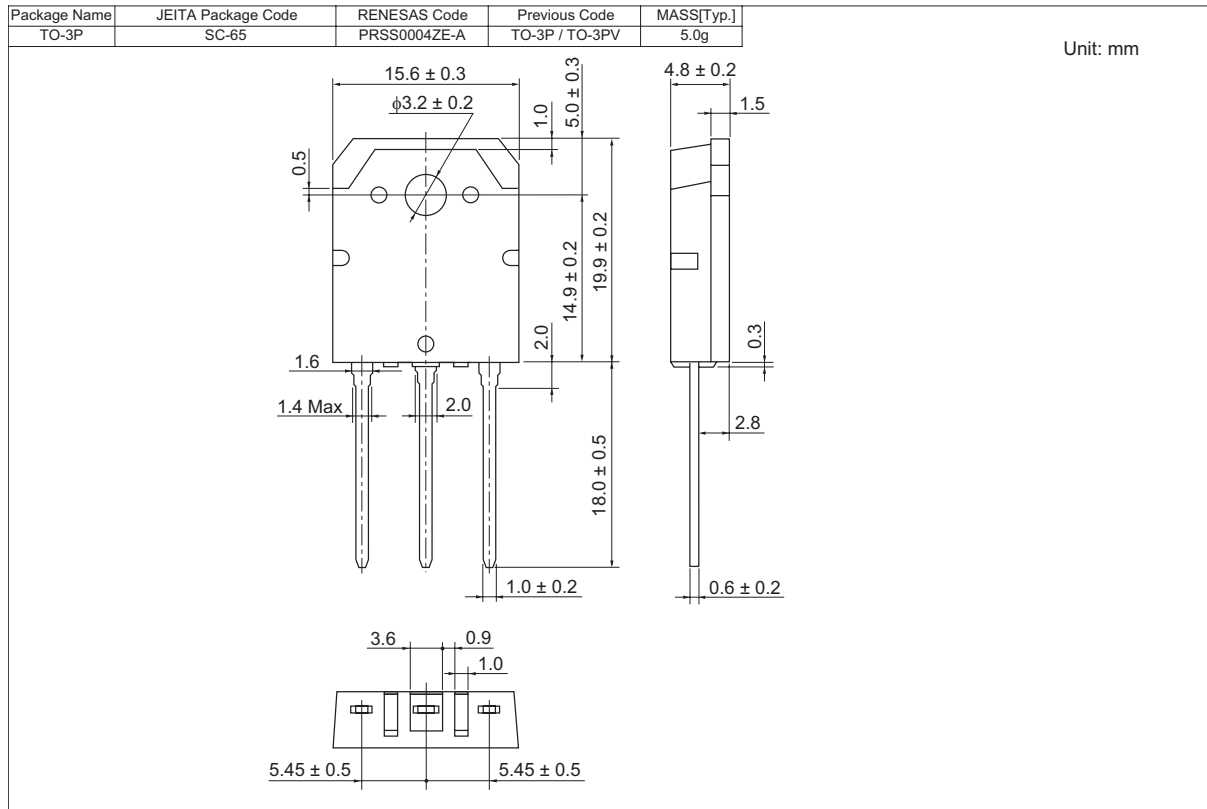
Electrical Characteristics

(Ta = 25°C)

Item	Symbol	Min	Typ	Max	Unit	Test conditions
Drain to source breakdown voltage	$V_{(BR)DSS}$	500	—	—	V	$I_D = 10 \text{ mA}$, $V_{GS} = 0$
Zero gate voltage drain current	I_{DSS}	—	—	1	μA	$V_{DS} = 500 \text{ V}$, $V_{GS} = 0$
Gate to source leak current	I_{GSS}	—	—	± 0.1	μA	$V_{GS} = \pm 30 \text{ V}$, $V_{DS} = 0$
Gate to source cutoff voltage	$V_{GS(off)}$	3.0	—	4.5	V	$V_{DS} = 10 \text{ V}$, $I_D = 1 \text{ mA}$
Static drain to source on state resistance	$R_{DS(on)}$	—	0.130	0.155	Ω	$I_D = 17.5 \text{ A}$, $V_{GS} = 10 \text{ V}$ ^{Note4}
Input capacitance	C_{iss}	—	4100	—	pF	$V_{DS} = 25 \text{ V}$
Output capacitance	C_{oss}	—	420	—	pF	$V_{GS} = 0$
Reverse transfer capacitance	C_{rss}	—	50	—	pF	$f = 1 \text{ MHz}$
Turn-on delay time	$t_{d(on)}$	—	50	—	ns	$I_D = 17.5 \text{ A}$
Rise time	t_r	—	99	—	ns	$V_{GS} = 10 \text{ V}$
Turn-off delay time	$t_{d(off)}$	—	144	—	ns	$R_L = 14.3 \Omega$
Fall time	t_f	—	93	—	ns	$R_g = 10 \Omega$
Total gate charge	Q_g	—	104	—	nC	$V_{DD} = 400 \text{ V}$
Gate to source charge	Q_{gs}	—	21	—	nC	$V_{GS} = 10 \text{ V}$
Gate to drain charge	Q_{gd}	—	46	—	nC	$I_D = 35 \text{ A}$
Body-drain diode forward voltage	V_{DF}	—	0.92	1.55	V	$I_F = 35 \text{ A}$, $V_{GS} = 0$ ^{Note4}
Body-drain diode reverse recovery time	t_{rr}	—	430	—	ns	$I_F = 35 \text{ A}$, $V_{GS} = 0$ $di_F/dt = 100 \text{ A}/\mu\text{s}$

Notes: 4. Pulse test

Package Dimensions



Ordering Information

Part Name	Quantity	Shipping Container
RJK5018DPK-00	360 pcs	Box (Tube)

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